SN74ALVCH16524 18-BIT REGISTERED BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES080E-JULY 1996-REVISED OCTOBER 2004

FEATURES

- Member of the Texas Instruments Widebus™
 Family
- UBT[™] Transceiver Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enable Mode
- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 3.2 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

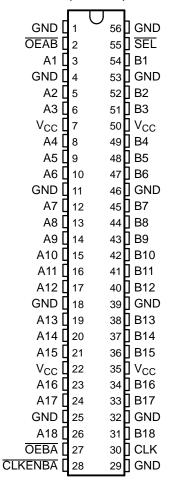
DESCRIPTION/ORDERING INFORMATION

This 18-bit universal bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

Data flow in each direction is controlled by output-enable (OEAB and OEBA) and clock-enable (CLKENBA) inputs. For the A-to-B data flow, the data flows through a single buffer. The B-to-A data can flow through a four-stage pipeline register path, or through a single register path, depending on the state of the select (SEL) input.

Data is stored in the internal registers on the low-to-high transition of the clock (CLK) input, provided that the appropriate CLKENBA input is low. The B-to-A data transfer is synchronized with CLK.

DGG OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SSOP - DL	Tube	SN74ALVCH16524DL	ALVCH16524	
-40 to 85°C	330P - DL	Tape and reel	SN74ALVCH16524DLR		
	TSSOP - DGG	Tape and reel	SN74ALVCH16524DGGR	ALVCH16524	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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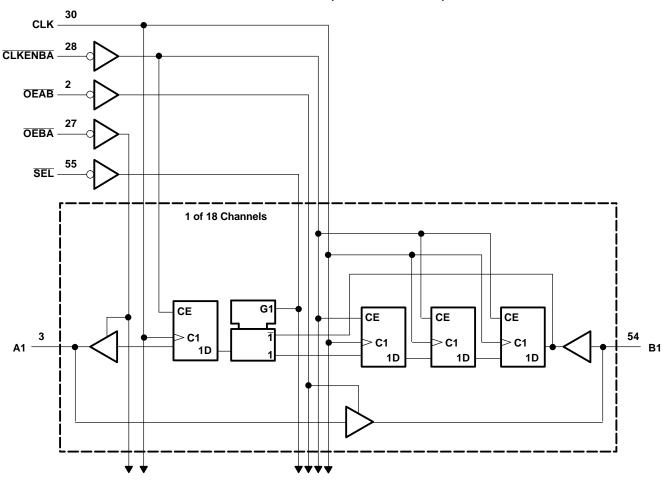


FUNCTION TABLE B-TO-A STORAGE (OEBA = L)

	INPUT	S		OUTPUT
CLKENBA	CLK	SEL	В	Α
Н	Χ	Χ	Χ	A ₀ ⁽¹⁾
L	\uparrow	Н	L	L
L	\uparrow	Н	Н	Н
L	\uparrow	L	L	∟(2)
L	\uparrow	L	Н	H ⁽²⁾

- (1) Output level before the indicated steady-state input conditions were established
- (2) Four positive CLK edges are needed to propagate data from B to A when SEL is low.

LOGIC DIAGRAM (POSITIVE LOGIC)





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ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	4.6	V
\/	Input voltage range	Except I/O ports ⁽²⁾	-0.5	4.6	V
VI	Input voltage range	I/O ports (2)(3)	-0.5	$V_{CC} + 0.5$	V
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V_{CC} or GND			±100	mA
0	Deckage thermal impedance (4)	DGG package		64	°C/W
θ_{JA}	Package thermal impedance (4)	DL package		56	°C/VV
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS(1)

			MIN	MAX	UNIT	
V _{CC}	Supply voltage		1.65	3.6	V	
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
VI	Input voltage		0	V_{CC}	V	
Vo	Output voltage		0	V_{CC}	V	
		V _{CC} = 1.65 V		-4		
	High lavel autout august	V _{CC} = 2.3 V		-12	A	
I _{OH}	High-level output current	V _{CC} = 2.7 V		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
	Low lovel output ourrent	V _{CC} = 2.3 V		12	mA	
l _{OL}	Low-level output current	V _{CC} = 2.7 V		12		
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate			10	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

⁽¹⁾ All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

³⁾ This value is limited to 4.6 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

P	ARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾ M	ΙAΧ	UNIT		
		$I_{OH} = -100 \mu A$	1.65 V to 3.6 V	V _{CC} - 0.2					
		I _{OH} = -4 mA	1.65 V	1.2					
		$I_{OH} = -6 \text{ mA}$	2.3 V	2					
V_{OH}			2.3 V	1.7			V		
		I _{OH} = -12 mA	2.7 V	2.2					
			3 V	2.4					
		I _{OH} = -24 mA	3 V	2					
		$I_{OL} = 100 \mu A$	1.65 V to 3.6 V			0.2			
		I _{OL} = 4 mA	1.65 V		0	.45			
V		$I_{OL} = 6 \text{ mA}$	2.3 V			0.4	١/		
V _{OL}	1 42 mA	2.3 V			0.7	V			
	I _{OL} = 12 mA	2.7 V			0.4				
		I _{OL} = 24 mA	3 V		0	.55			
I		$V_I = V_{CC}$ or GND	3.6 V			±5	μΑ		
		V _I = 0.58 V	1.65 V	25					
		V _I = 1.07 V	1.65 V	-25					
		V _I = 0.7 V	2.3 V	45					
I _{I(hold)}		V _I = 1.7 V	2.3 V	-45			μΑ		
		V _I = 0.8 V	3 V	75					
		V _I = 2 V	3 V	-75					
		$V_1 = 0$ to 3.6 $V^{(2)}$	3.6 V		±:	500			
I _{OZ} (3)		$V_O = V_{CC}$ or GND	3.6 V		-	±10	μΑ		
I _{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			40	μΑ		
ΔI_{CC}		One input at V_{CC} - 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V		-	750	μΑ		
C _i	Control inputs	$V_I = V_{CC}$ or GND	3.3 V	_	3		pF		
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	3.3 V		7		pF		

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V _{CC} =	1.8 V	V _{CC} = : ± 0.2		V _{CC} =	2.7 V	V _{CC} = 3 ± 0.3		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f _{clock}	f _{clock} Clock frequency			(1)		120		125		150	MHz	
t _w	Pulse duration, CLK high or low				3.2		3.2		3		ns	
		B data before CLK↑	(1)		1.5		1.2		1.1			
t _{su}	Setup time	SEL before CLK↑	(1)		2.7		2.4		2.1		ns	
		CLKENBA before CLK↑	(1)		2.7		2.6		2			
		B data after CLK↑	(1)		1		0.6		1.2			
t _h	t _h Hold time	SEL after CLK↑	(1)		0.5		0.2		0.8		ns	
		CLKENBA after CLK↑	(1)		0.1		0.1		0.3			

⁽¹⁾ This information was not available at the time of publication.

⁽¹⁾ All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. (2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to

⁽³⁾ For I/O ports, the parameter $I_{\mbox{\scriptsize OZ}}$ includes the input leakage current.



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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V	V _{CC} = 3.3 V ± 0.3 V	UNIT
	(INFOT)	(OUTPUT)	MIN TYP	MIN	MAX	MIN MAX	MIN MAX	(
f _{max}			(1)	120		125	150	MHz
	Α	В	(1)	1	3.9	3.8	1 3.2	
t _{pd}	CLK	A	(1)	1	6.1	6.2	1 5.2	ns
t _{en}	OEAB or OEBA	A or B	(1)	1	6.1	6.1	1 5.1	ns
t _{dis}	OEAB or OEBA	A or B	(1)	1	6.3	5.4	1 4.9	ns ns

⁽¹⁾ This information was not available at the time of publication.

OPERATING CHARACTERISTICS

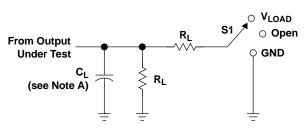
 $T_A = 25^{\circ}C$

	PARAMET	ΓER	TEST C	CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
0	Power dissipation	Outputs enabled	0 50 -5	4 40 MHz	(1)	160	160	
C_{pd}	capacitance	Outputs disabled	$C_L = 50 \text{ pF},$	f = 10 MHz	(1)	160	160	pF

⁽¹⁾ This information was not available at the time of publication.



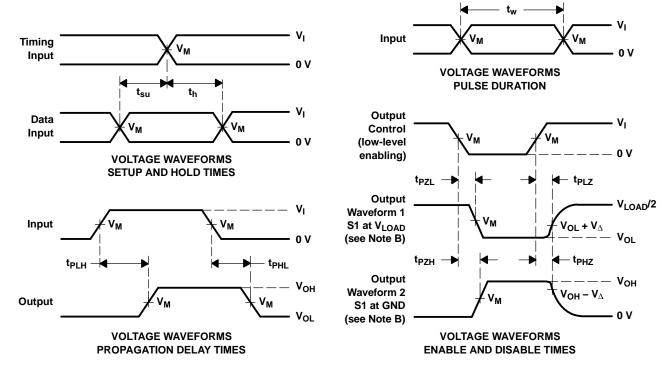
PARAMETER MEASUREMENT INFORMATION



TEST	S 1
t _{pd}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

V	IN	PUT	V _M V _{LOAD}			ь	V
V _{CC}	VI	t _r /t _f	VМ	VLOAD	CL	R _L	$V_{\!\scriptscriptstyle \Delta}$
1.8 V ± 0.15 V	V _{CC}	≤ 2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74ALVCH16524DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16524
SN74ALVCH16524DL.B	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16524

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ALVCH16524DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ALVCH16524DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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